

DATA vs TIME

Look at Trend versus Time

Trend Chart

Model Distribution vs Time

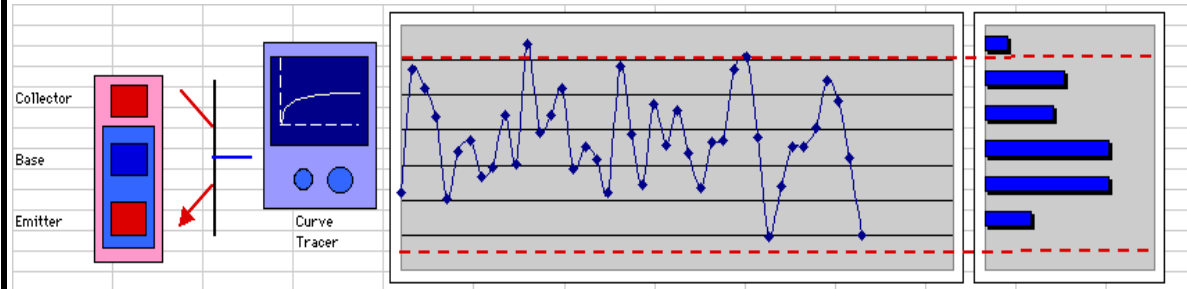
Time Series Modeling
Autocorrelation
Partial Autocorrelation
Moving Average
EWMA
AR
MA
ARIMA

Study Sources -Time Variation

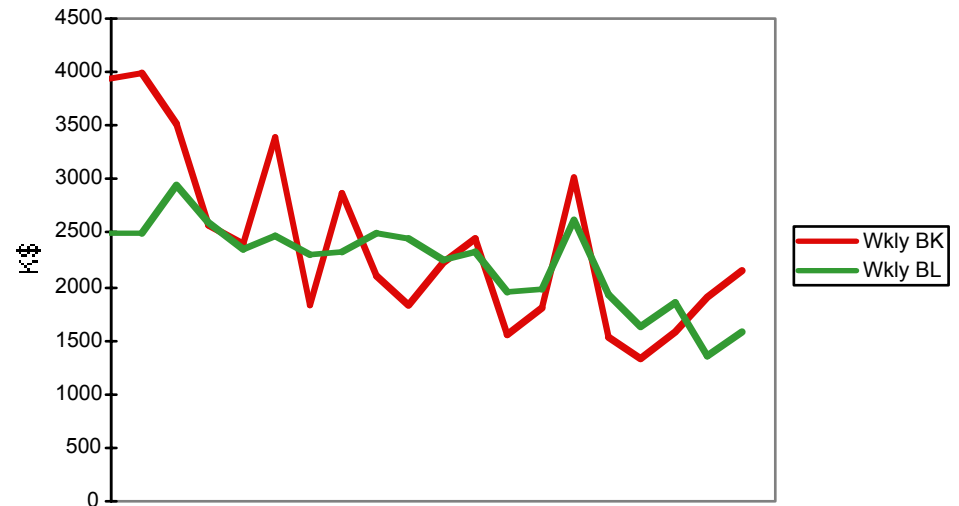
Gauge Capability
Variance Components Analysis

Compare Trend to Limits

Control Charts
X-Bar
R, S
Individuals
Moving R
EWMA



Weekly Bookings and Billings



Open a New Worksheet / Type: Excel or Copy from Excel (stockprices.xls)

Microsoft Excel - stockprices.xls

File Edit View Insert Format Tools Data Window Help Acrobat

Geneva 9 B I U

E68 = 27.31

	A	B	C	D	E	F	G	H	I	J	K	L
1												
2		Mot	ONNN	Lucent	Dow							
3	Aug-15-02	12.3	2	1.5	29.84							
4	Aug-16-02	12.9	1.93	1.47	29.51							
5	Aug-19-02	13.38	2.08	1.45	29.16							
6	Aug-20-02	12.67	2.25	1.45	29.66							
7	Aug-21-02	13.38	2.14	1.43	28.74							
8	Aug-22-02	13.53	2.25	1.47	29.18							
9	Aug-23-02	13	2.2	1.58	29.71							
10	Aug-26-02	13	2.08	1.5	29.15							
11	Aug-27-02	12.78	2.16	1.87	29.75							
12	Aug-28-02	12.1	1.94	1.89	30.02							
13	Aug-29-02	12.31	1.94	1.69	29.26							
14	Aug-30-02	12	1.98	1.82	29.87							
15	Nov-01-02	9.42	1.43	1.14	26.48							
16	Nov-04-02	9.98	1.43	1.18	26							
17	Nov-05-02	9.85	1.52	1.22	26.41							
18	Nov-06-02	9.62	1.58	1.32	27.7							
19	Nov-07-02	9.02	1.53	1.22	26.5							
20	Nov-08-02	8.8	1.59	1.21	26.53							
21	Nov-11-02	8.38	1.5	1.08	25.47							
22	Nov-12-02	8.75	1.59	1.12	26.16							
23	Nov-13-02	8.75	1.54	1.11	26.5							
24	Nov-14-02	9.07	1.65	1.18	27.85							
25	Oct-01-02	10.48	1.13	0.76	29.8							
26	Oct-02-02	10.15	1.14	0.79	27.25							
27	Oct-03-02	10.46	1.07	0.75	26.69							
28	Oct-04-02	10.01	0.91	0.75	26.23							
29	Oct-07-02	9.5	0.96	0.7	25.45							
30	Oct-08-02	9.75	1	0.69	25.92							
31	Oct-09-02	8.3	1.12	0.67	24.5							
32	Oct-10-02	9.09	1.26	0.7	25.15							
33	Oct-11-02	9.97	1.31	0.58	26.77							
34	Oct-14-02	10.1	1.09	0.69	26.76							

Sheet1 Sheet2 Sheet3

Select destination and press ENTER or choose Paste

Sum=2694.94

Paste into Minitab

MINITAB - Untitled

File Edit Manip Calc Stat Graph Editor Window Help

Session

11/15/2002 5:42:29 AM

Welcome to Minitab, press F1 for help.

Worksheet 1 ***

	C1-T	C2	C3	C4	C5	C6	C7	C8	C9	C10	C11	C12	C13	C14	C15	C16
	Date	Mot	ONNN	Lucent	Dow											
1	Aug-15-02	12.30	2.00	1.50	29.84											
2	Aug-16-02	12.90	1.93	1.47	29.51											
3	Aug-19-02	13.38	2.08	1.45	29.16											
4	Aug-20-02	12.67	2.25	1.45	29.66											
5	Aug-21-02	13.38	2.14	1.43	28.74											
6	Aug-22-02	13.53	2.25	1.47	29.18											
7	Aug-23-02	13.00	2.20	1.58	29.71											
8	Aug-26-02	13.00	2.08	1.50	29.15											
9	Aug-27-02	12.78	2.16	1.87	29.75											

Project Man...

Current Worksheet: Worksheet 1

5:42 AM

- Stat
- Graph
- Editor
- Window
- Basic Statistics
- Regression
- ANOVA
- DOE
- Control Charts
- Quality Tools
- Reliability/Survival
- Multivariate
- Time Series**
- Tables
- Nonparametrics
- EDA
- Power and Sample Size

Trend Chart

Time Series Plot...

Trend Analysis...

Decomposition...

Moving Average...

- OR -

- Graph
- Editor
- Window
- Layout...
- Plot...
- Time Series Plot...**
- Chart...
- Histogram...
- Boxplot...
- Matrix Plot...
- Draftsman Plot...
- Contour Plot...
- 3D Plot...
- 3D Wireframe Plot...
- 3D Surface Plot...
- Dotplot...
- Pie Chart...
- Marginal Plot...
- Probability Plot...
- Stem-and-Leaf...
- Character Graphs

Time Series Plot

	C2	Mot
C3	ONNN	
C4	Lucent	
C5	Dow	

Graph variables:

Graph **Y**

1 Mot

2

3

Time Scale

☒ Index

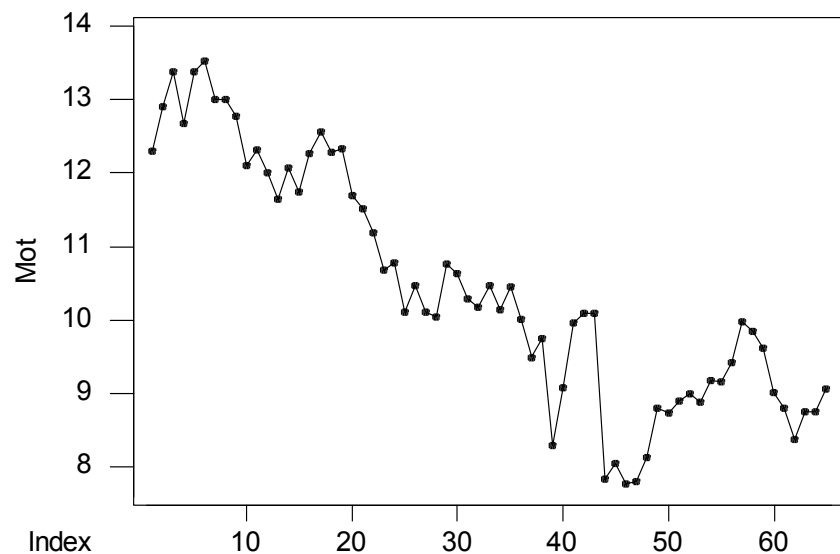
☐ Date/Time Stamp:

☐ Calendar:

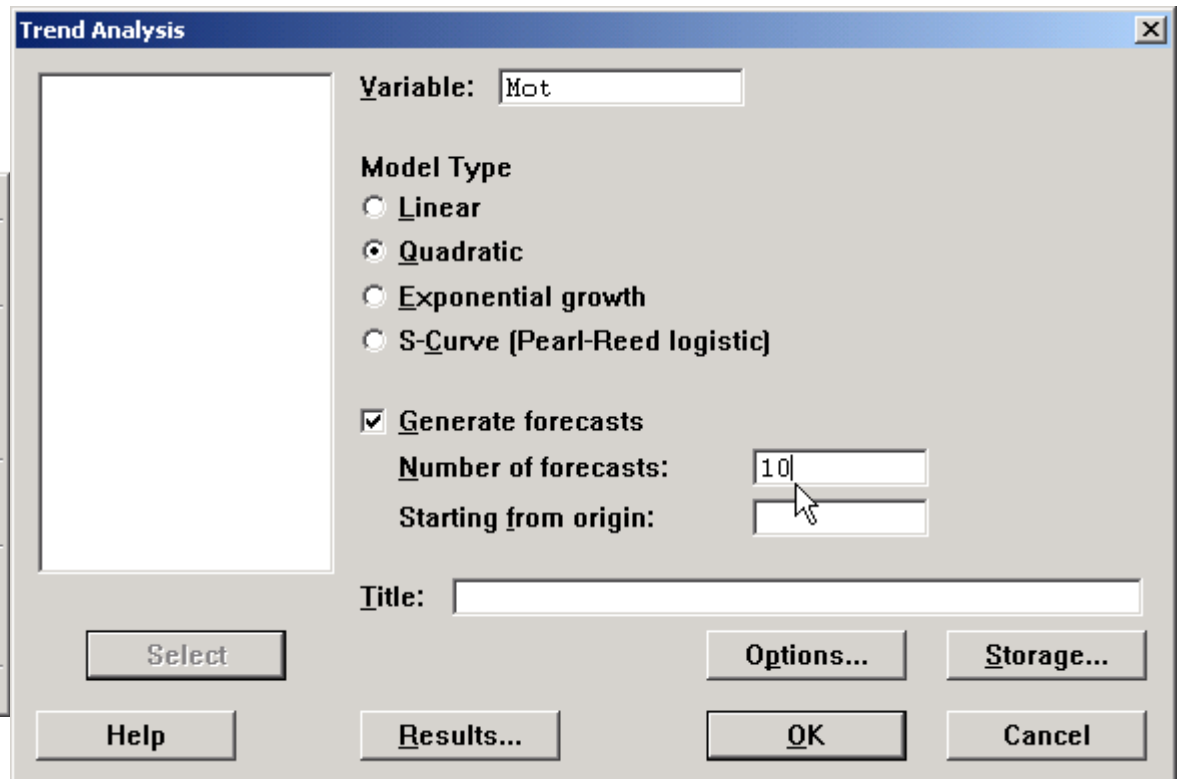
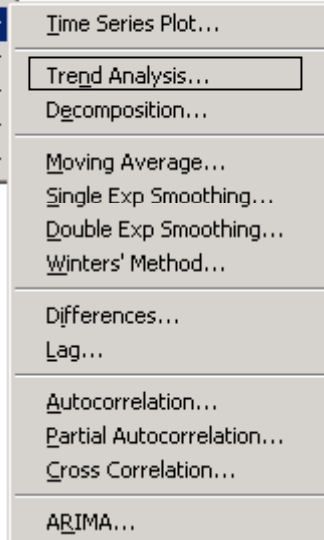
☐ Clock:

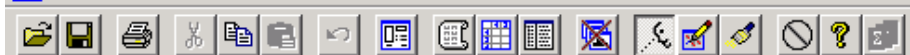
Data display:

Item	Display	For each	Group variables
1	Symbol	Graph	
2	Connect	Graph	
3			



EXAMPLE – STOCKS

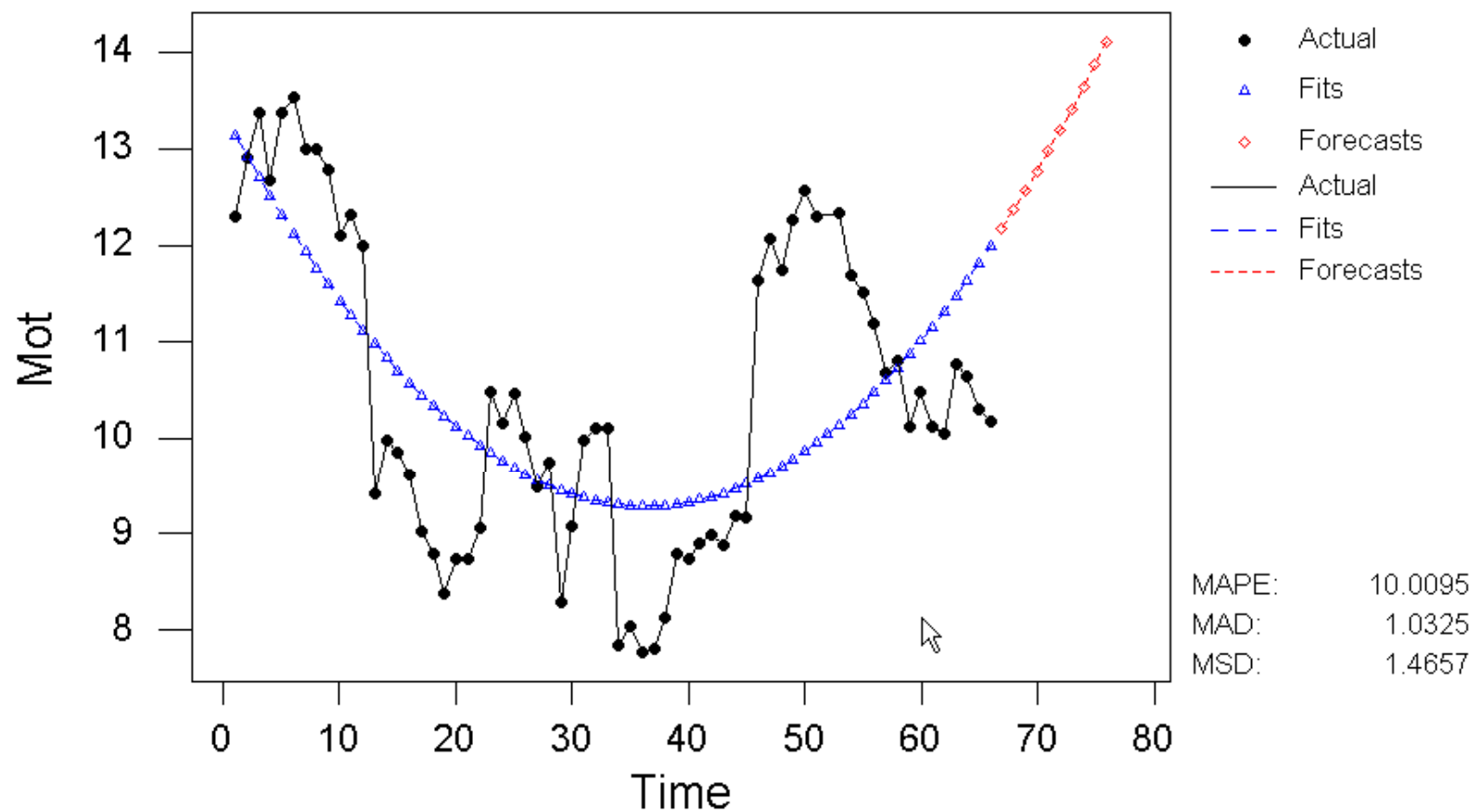




Trend Analysis for Mot

Quadratic Trend Model

$$Y_t = 13.3557 - 0.223221 \cdot t + 3.07 \text{E-}03 \cdot t^{**}2$$



Stat Graph Editor Window

Basic Statistics ▶
Regression ▶
ANOVA ▶
DOE ▶
Control Charts ▶
Quality Tools ▶
Reliability/Survival ▶
Multivariate ▶
Time Series ▶
Tables ▶
Nonparametrics ▶
EDA ▶
Power and Sample Size ▶

Time Series Plot...

Trend Analysis...

Decomposition... ←

Moving Average...

Single Exp Smoothing...

Double Exp Smoothing...

Winters' Method...

Differences...

Lag...

Autocorrelation...

Partial Autocorrelation...

Cross Correlation...

ARIMA...

Decomposition

Variable: Mot

Seasonal length: 15

Model Type

☒ Multiplicative

☐ Additive

Model Components

☒ Trend plus seasonal

☐ Seasonal only

First obs. is in seasonal period:

1

☒ Generate forecasts

Number of forecasts:

10

Starting from origin:

Title:

Select

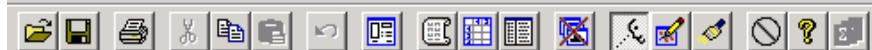
Results...

Storage...

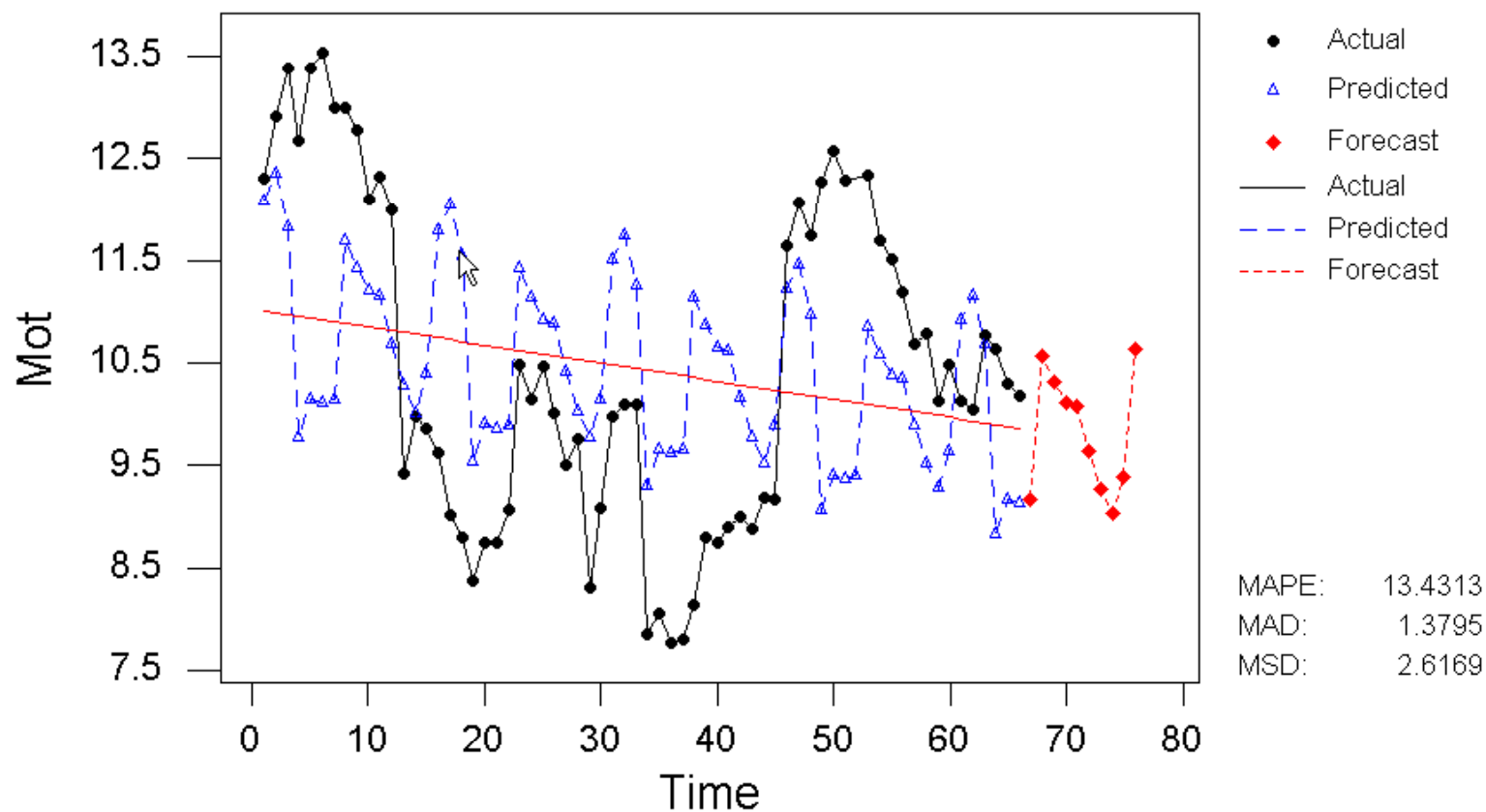
Help

OK

Cancel



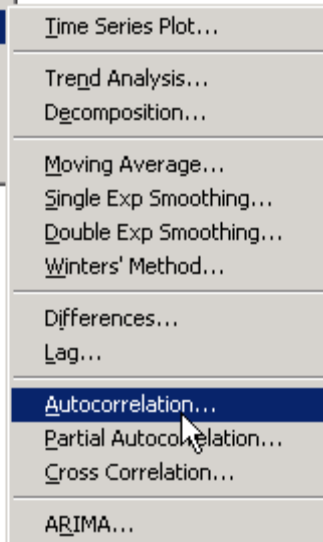
Decomposition Fit for Mot



Autocorrelation

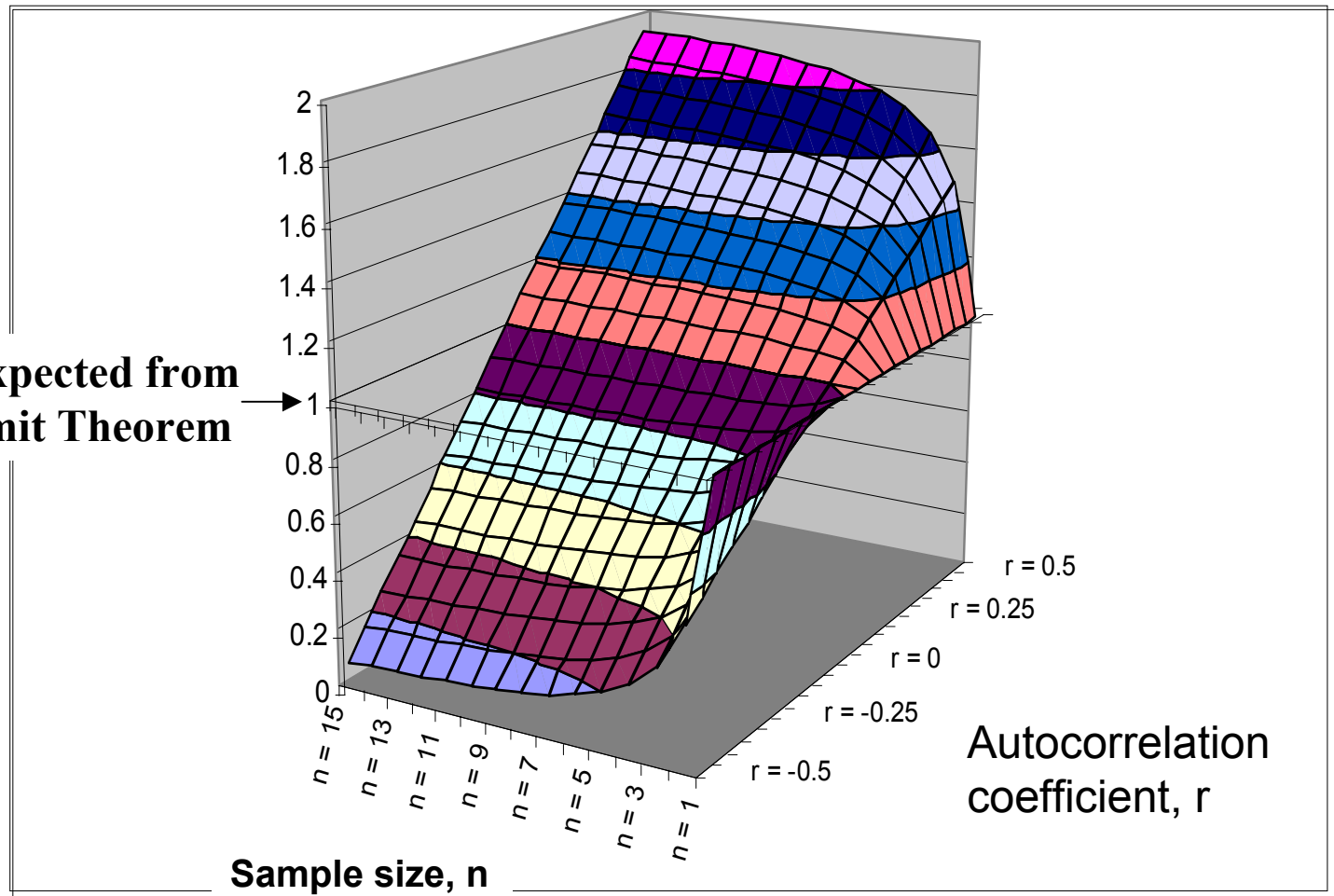


The autocorrelation correlogram shows the correlation between values that vary over time, with varying lags.

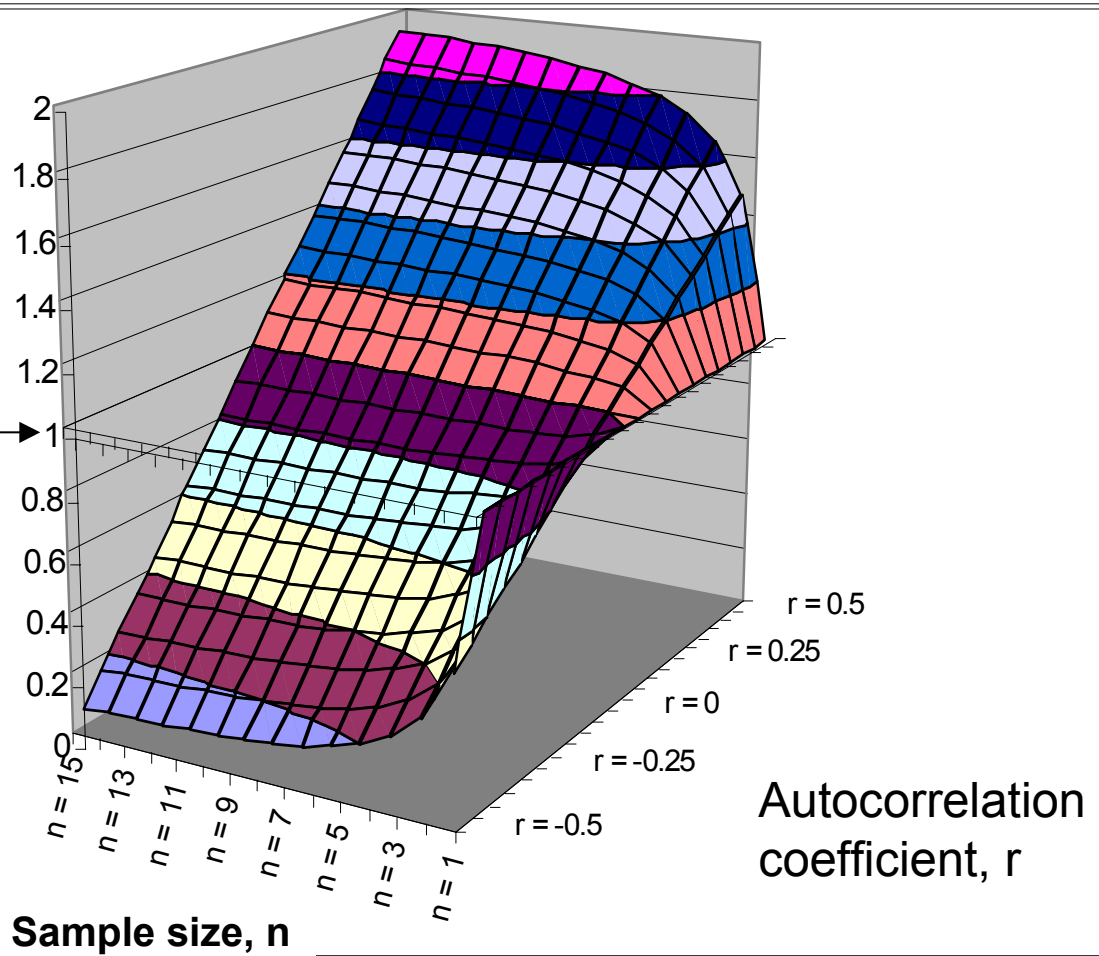


Autocorrelation of lag 1 is the correlation of each observation with the prior observation. The Central Limit Theorem assumes independence, which relates to zero autocorrelation. If there is autocorrelation, $\text{variance}(\bar{y}) = C\sigma^2/n = C * (\text{variance of means from C.L.T.})$. C is the ratio of observed variance of means to that expected from the Central Limit Theorem. C can range from 0 to 2, depending on the autocorrelation and the sample size. The autocorrelation for lag of 1 can range from -0.5 to $+0.5$.

**Variance expected from
Central Limit Theorem**



**Variance expected from
Central Limit Theorem**



OVERVIEW

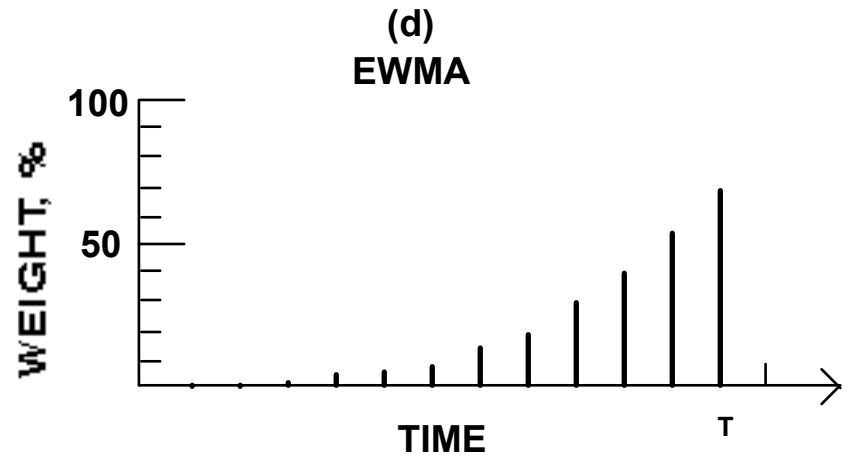
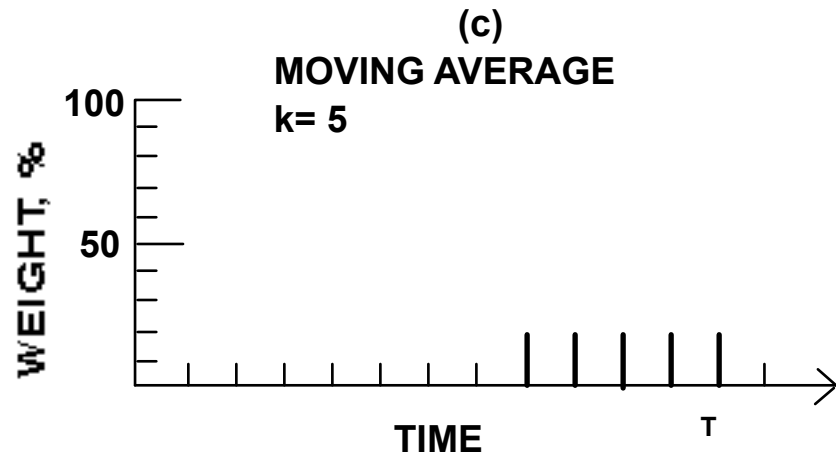
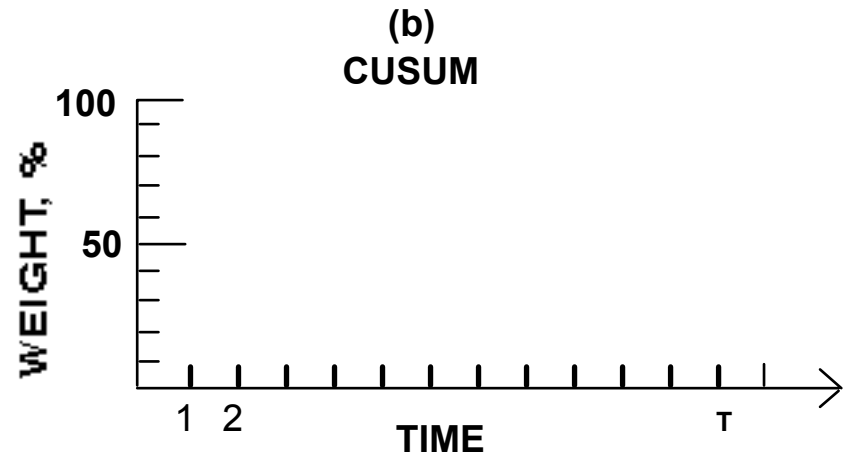
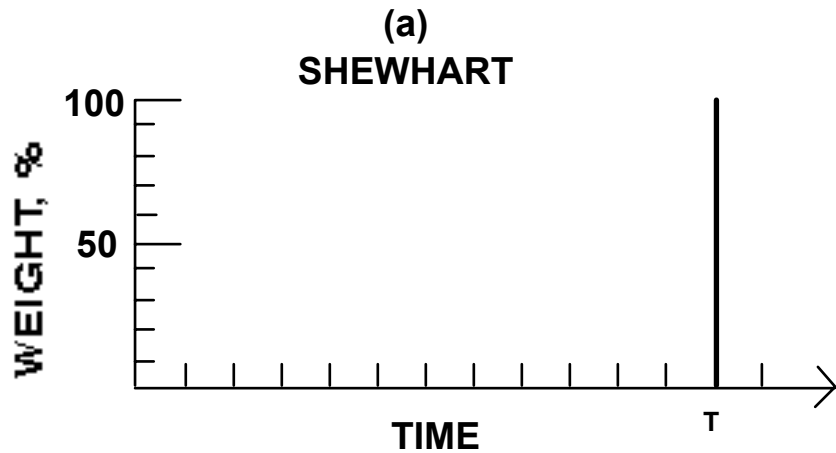
DATA VS. **T**IME

- Complications of S.P.C. in Semiconductor Processing
- Identifying and Prioritizing Critical Parameters
- Gauge Capability
- Levels of Variation
- Control Charting
- Times Series Modeling

COMPLICATIONS OF S.P.C. IN SEMICONDUCTOR PROCESSING

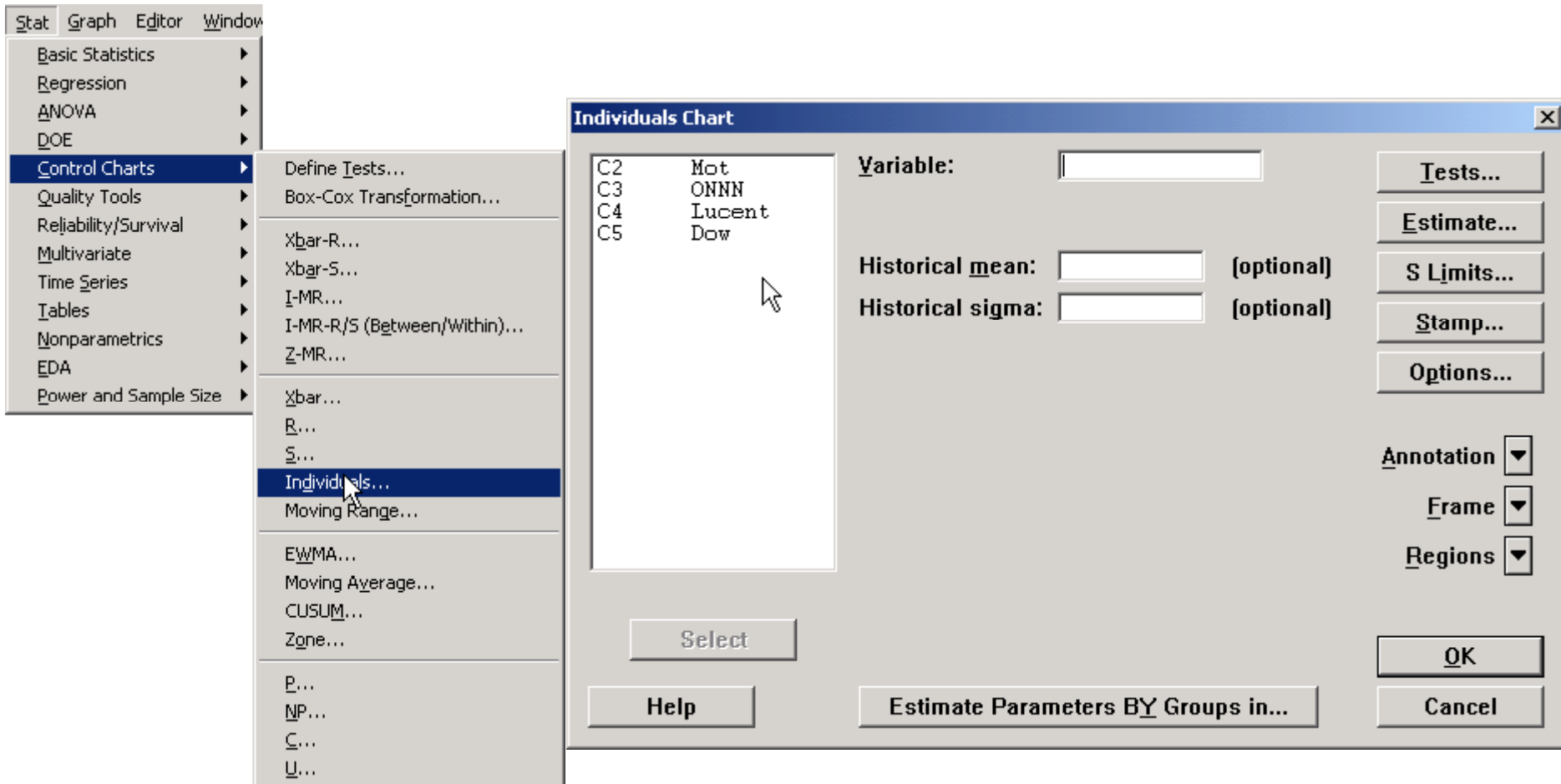
1. Indirect relationship of process parameters to device performance
 - Most IC fabrication operations involve chemical inputs and outputs, that relate indirectly to device performance (electrical outputs)
 - Effects on SPC - in many cases, spec limits were set somewhat arbitrarily (that is, not based upon the effect on device performance)
2. Quantity of process operations, input and output parameters
 - There are literally hundreds or thousands of process parameters (input and output) that can effect the product
 - Effects on SPC - there are insufficient resources to completely characterize each parameter

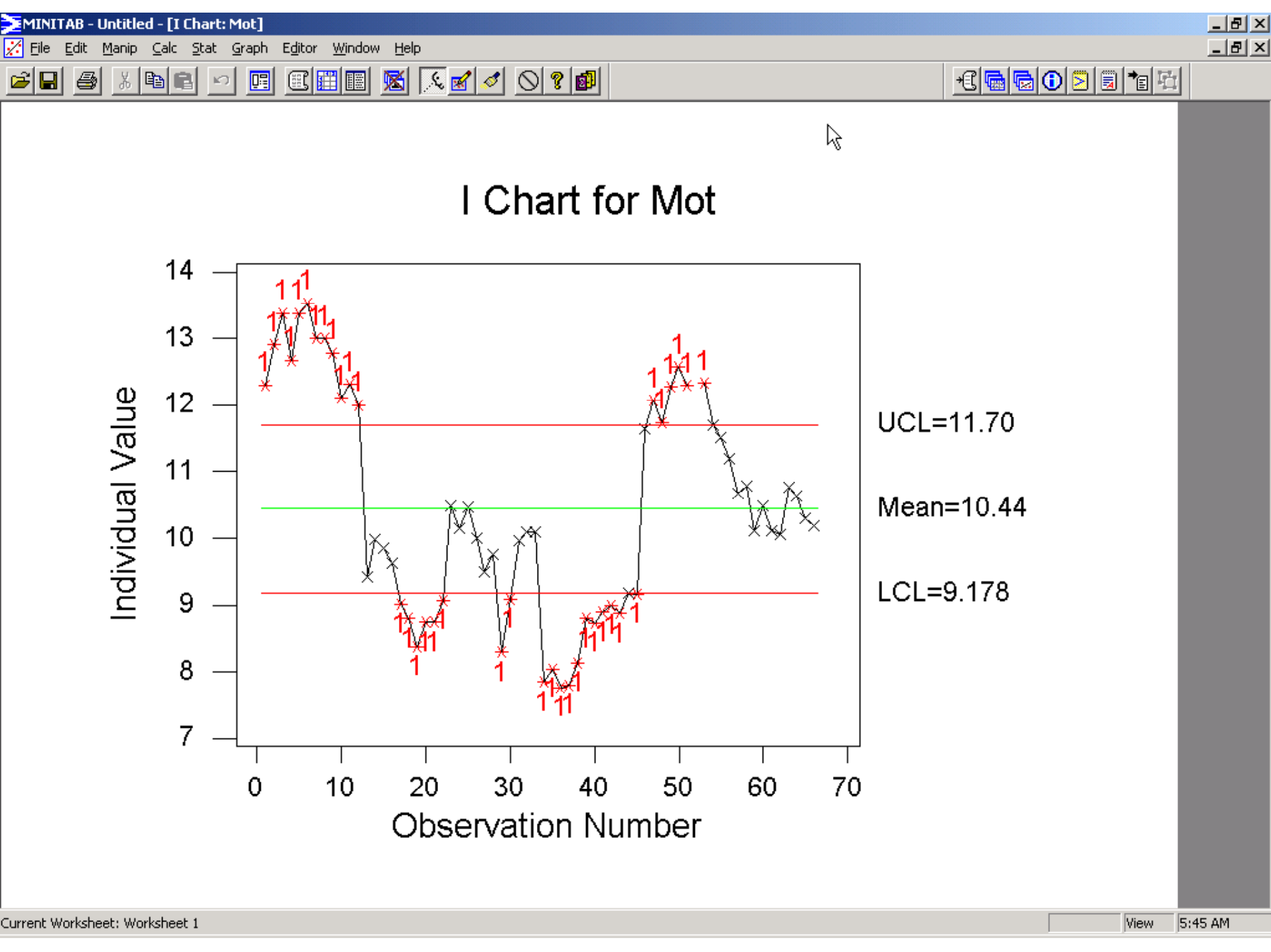
THE EXPONENTIALLY WEIGHTED MOVING AVERAGE



SPC – Individuals Chart

(Applied to stock prices...)





SPC is an ongoing Statistical Test

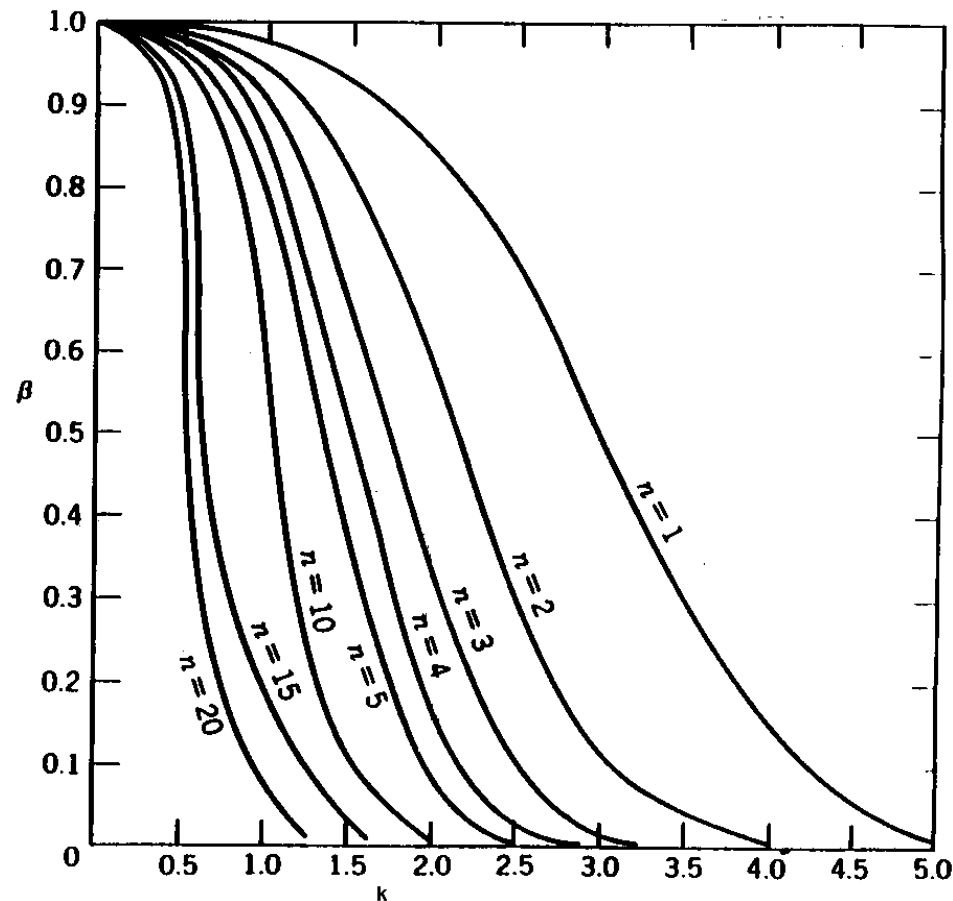
RISKS

REALITY

YOUR CONCLUSION

	There <u>is</u> a difference	There is <u>not</u> a difference
There <u>is</u> a difference	(WAY TO GO!!!)	α - RISK (TYPE I ERROR)
There is <u>not</u> a difference	β - RISK (TYPE II ERROR)	(WAY TO GO!!!)

BETA RISK FOR $\bar{X}$ CONTROL CHART



Operating characteristic curves for the $\bar{x}$ chart with 3-sigma limits. $\beta = p$ (not detecting a shift of $k\sigma$ in the mean on the first sample following the shift).

Note: Over time, the beta risk decreases.



SPC – EWMA Chart

EWMA Chart

C2	Mot
C3	ONNN
C4	Lucent
C5	Dow

Data are arranged as

☒ **Single column:**

Subgroup size:
(use a constant or an ID column)

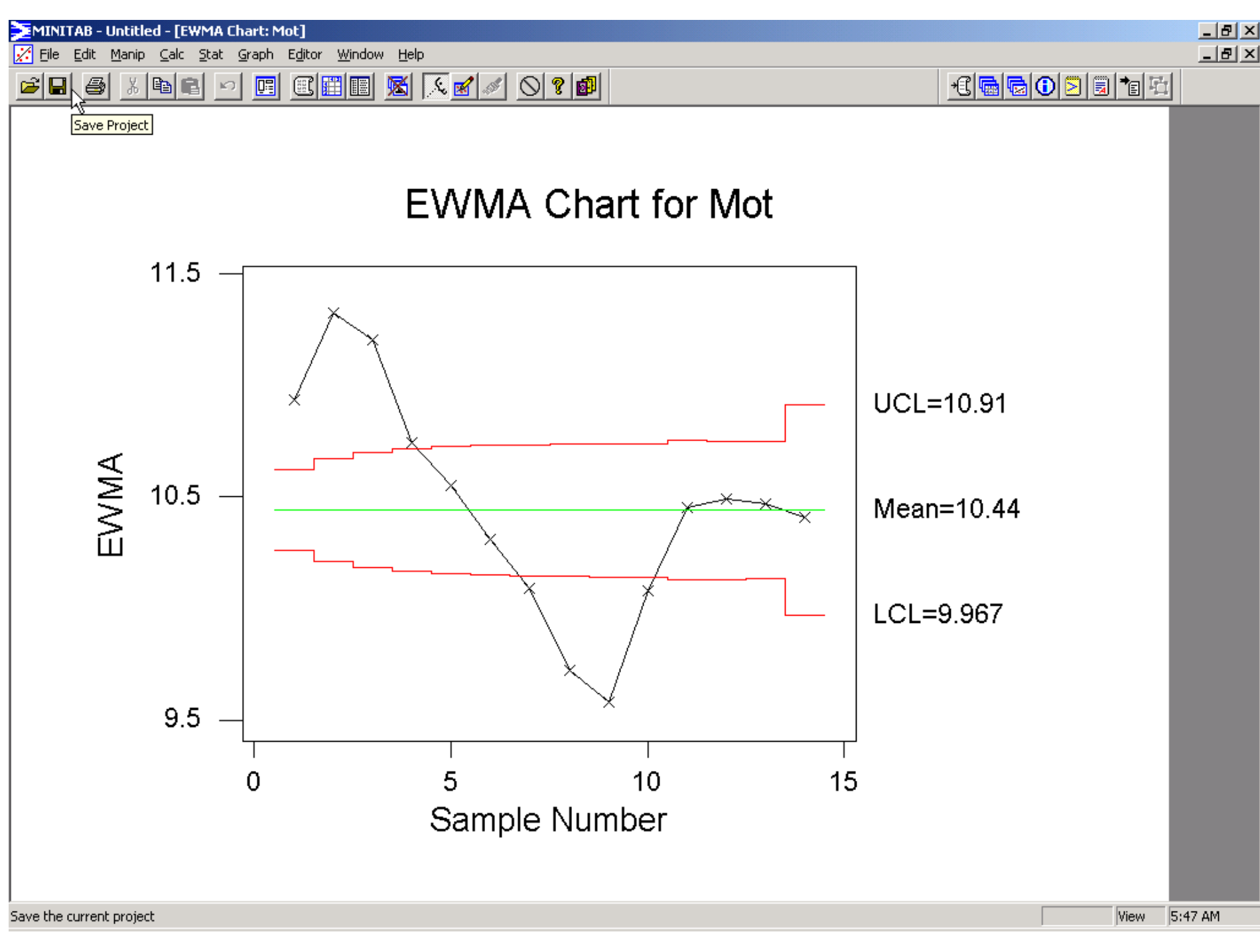
☐ **Subgroups across rows of:**

Weight for EWMA:

Historical mean: [optional]

Historical sigma: [optional]

Annotation ▼ **Frame** ▼ **Regions** ▼



COMPLICATIONS OF S.P.C. IN SEMICONDUCTOR PROCESSING

3. Nested variance

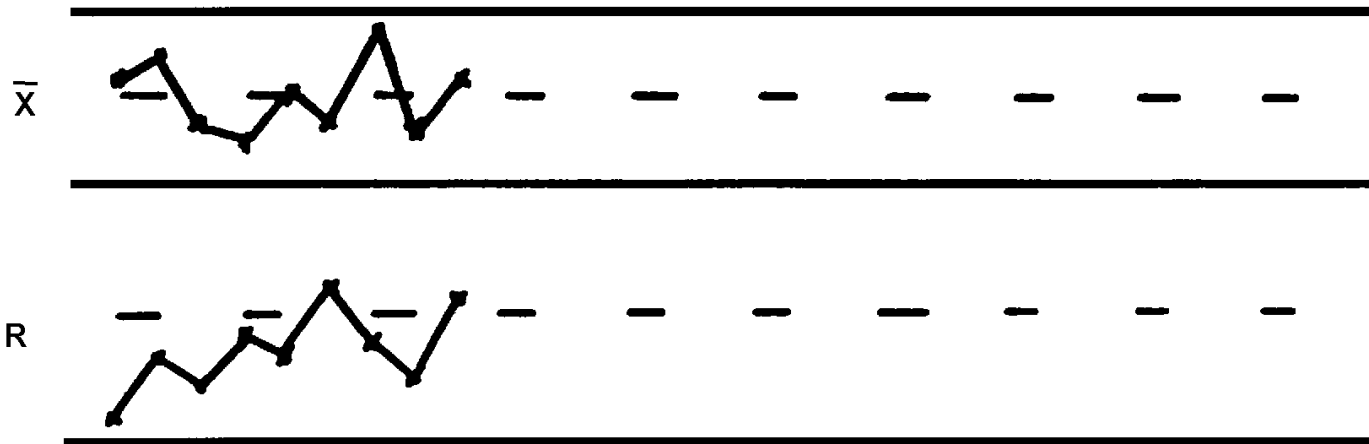
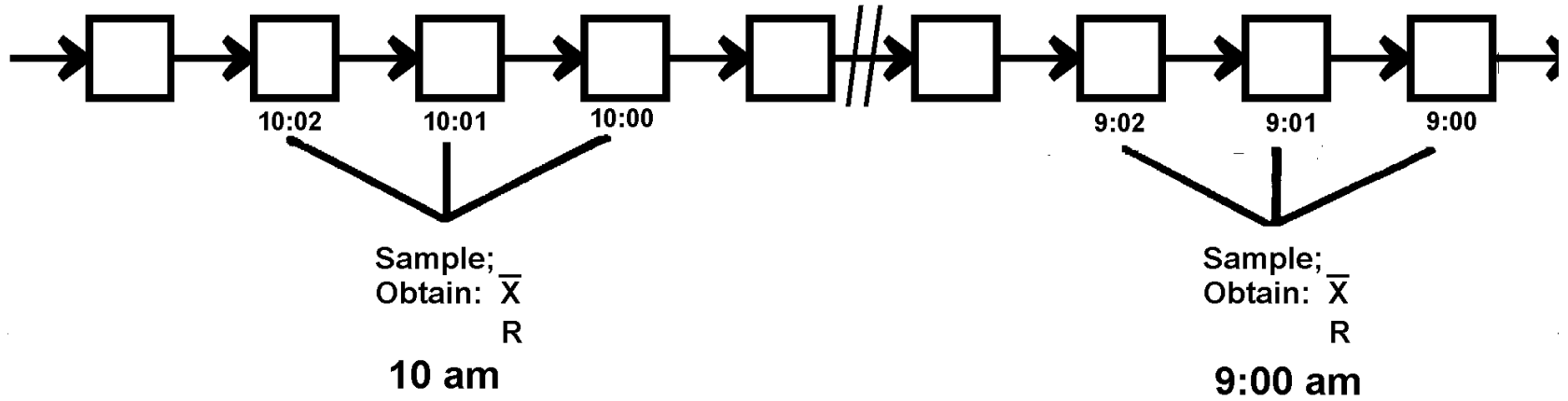
- There are at least three levels of variation (lot-lot, wafer–wafer, within–wafer)
- Effects on SPC - requirement to control multiple levels of variation; complications in establishing control limits. (Advantage: can provide clues to cause of out–of–control condition; can use to establish response procedures)

4. Non-normal distributions

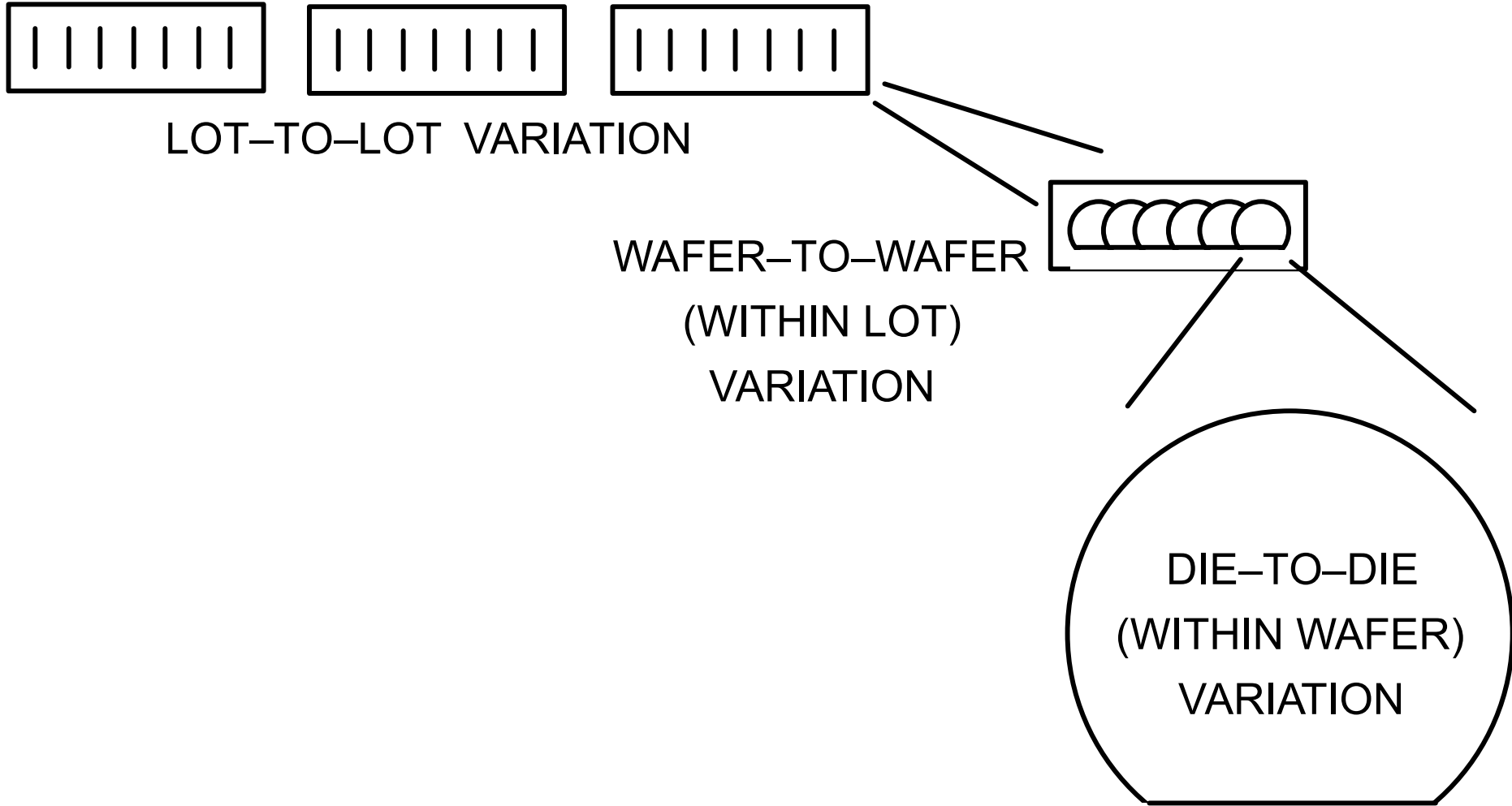
- Several key parameters have non-normal distributions (examples: HFE, contact resistance, sheet resistance)
- Effects on SPC - "X-bar" (lot means) may not approach normality (central limit theorem), because lot-lot is often the only level of variation with respect to time

SHEWHART CONTROL CHART MODEL

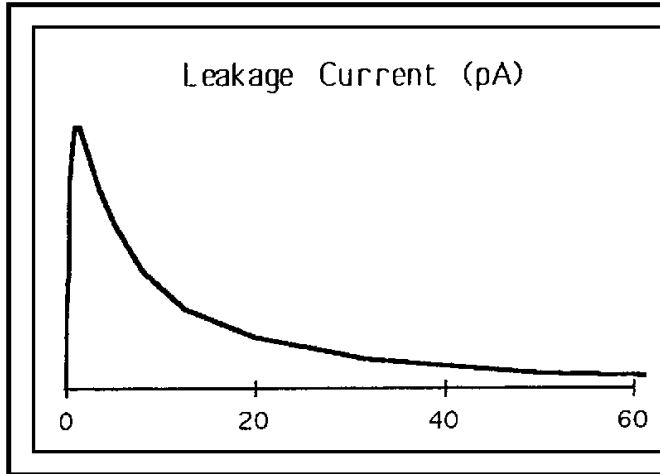
Assembly Line:



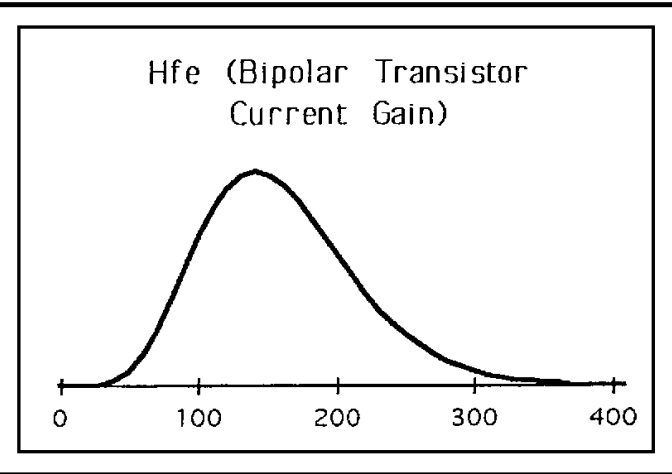
NESTED VARIANCE IN I.C. MANUFACTURING:



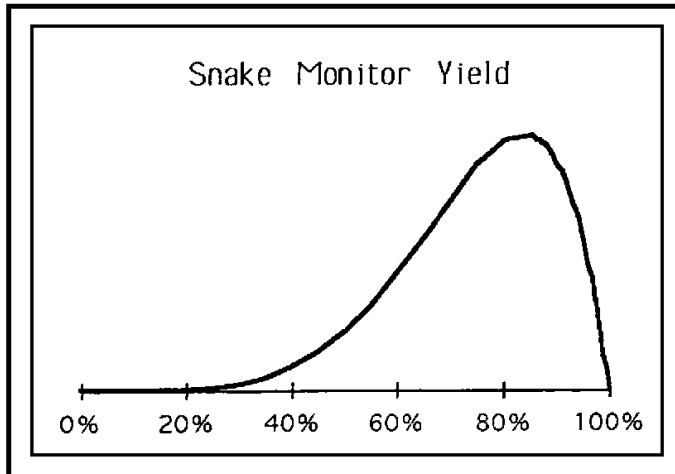
NON-NORMAL DISTRIBUTION IN SEMICONDUCTOR PROCESSING



LOG-NORMAL DISTRIBUTION

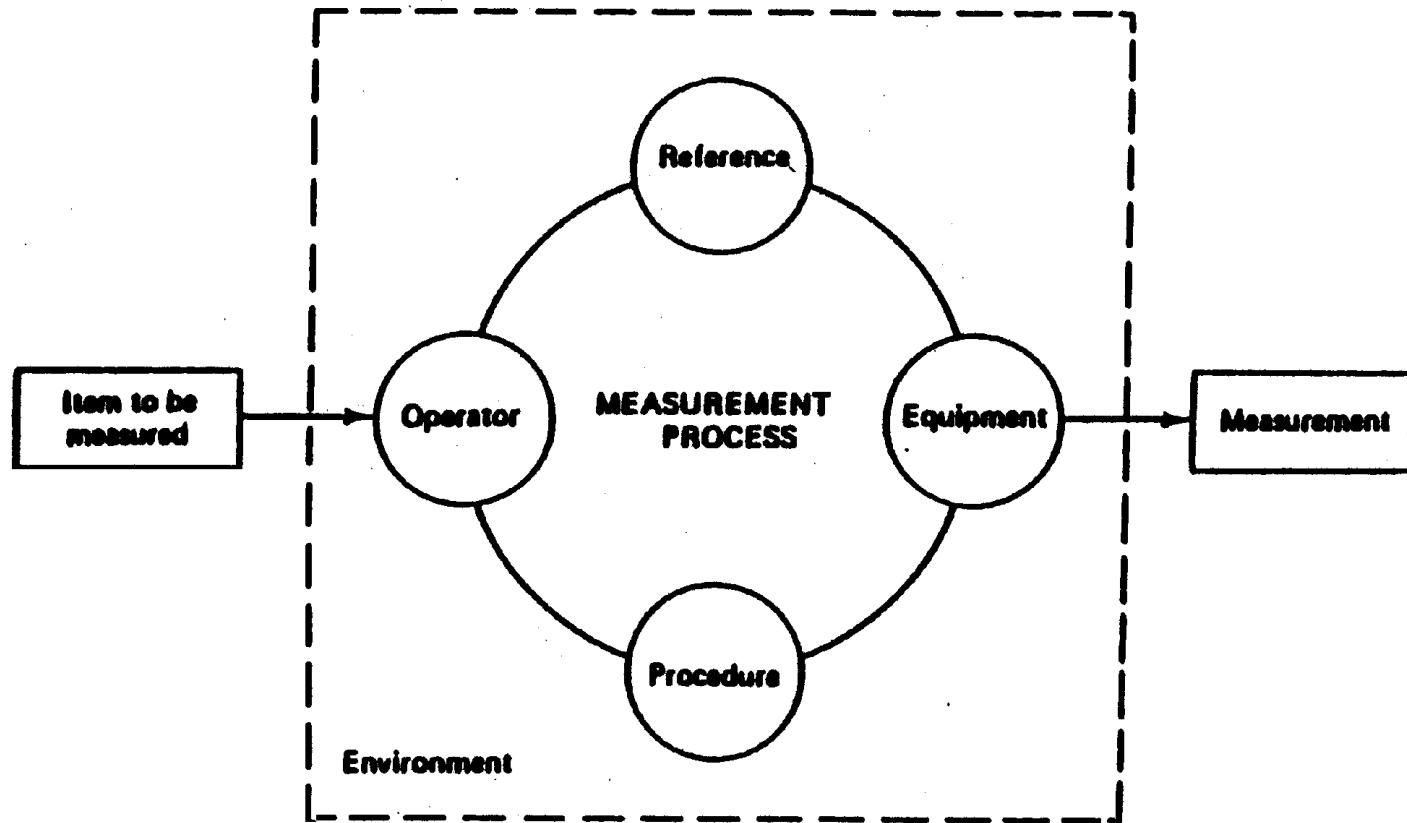


GAMMA DISTRIBUTION



BETA DISTRIBUTION

MEASUREMENT AS A PRODUCTION PROCESS CONCEPT



ACCURACY AND **P**RECISION

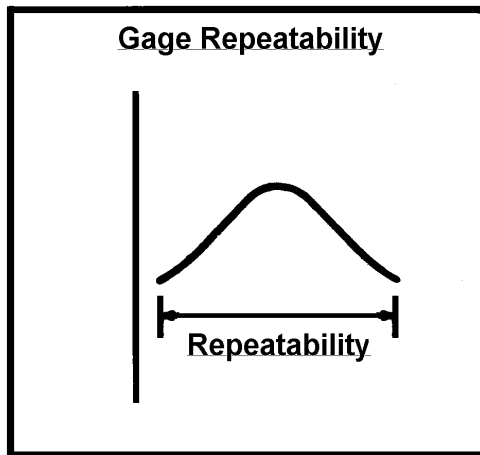
Accuracy = Closeness to the truth

Precision = Closeness of replicate measurements

PRECISION:

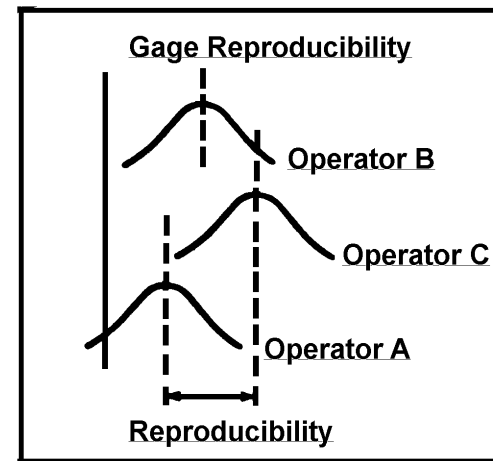
REPEATABILITY AND REPRODUCIBILITY

Precision — The degree of agreement among individual measurements of the same sample



Gage Repeatability

Gage Repeatability is the variation in measurements obtained when one operator uses the same gage for measuring the identical characteristics of the same parts.



Gage Reproducibility

Gage Reproducibility is the variation in the average of measurements made by different operators using the same gage when measuring identical characteristics of the same parts.

P RECISION/TOLERANCE RATIO

P/T RATIO

The P/T value is the ratio between the measurement precision estimate and the tolerance of the characteristic being measured.

$$\text{P/T Ratio} = \frac{6 \sigma_E}{\text{Total Tolerance}}$$

Where σ_E is the standard deviation due to measurement variability.

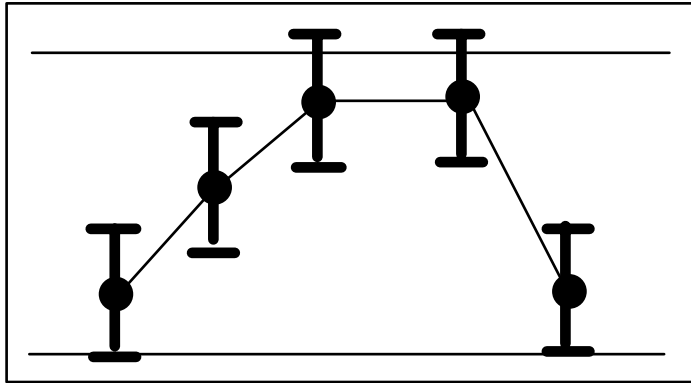
Assumption:

Measurement errors are independent

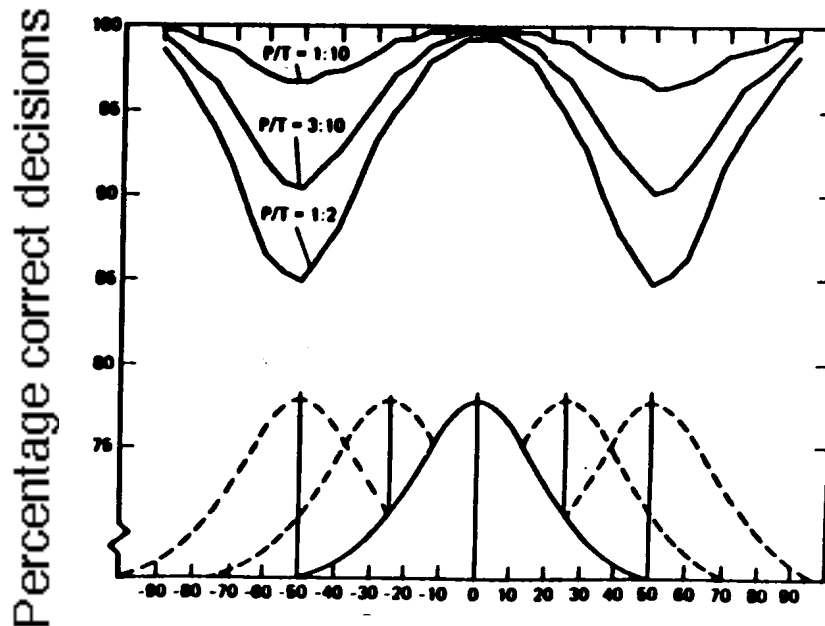
Measurement errors are normally distributed

Measurement error is independent of part size

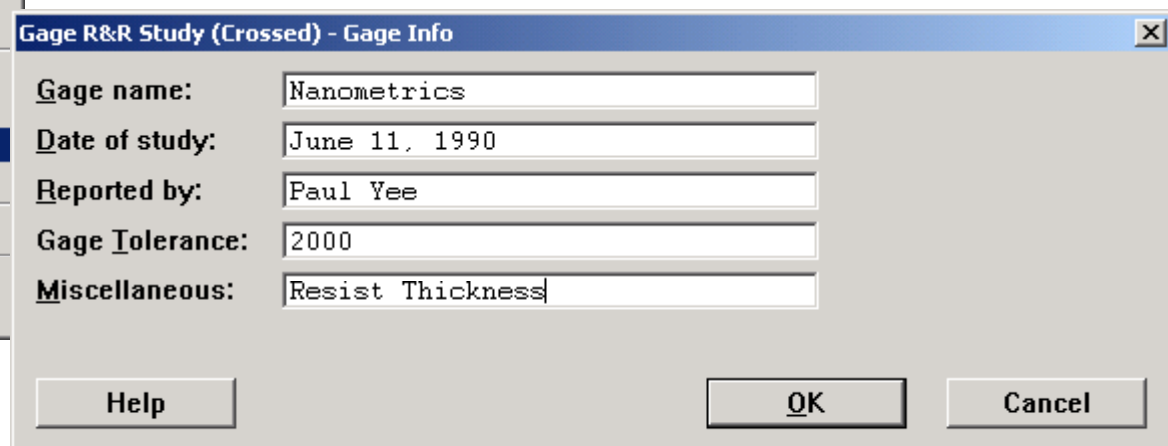
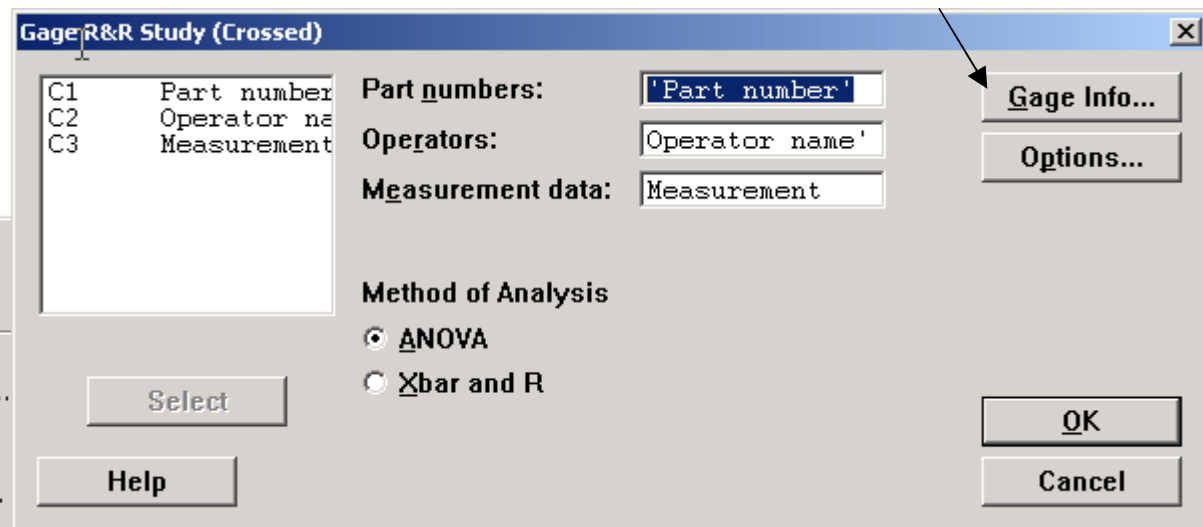
EFFECT OF P/T RATIO ON DECISION MAKING



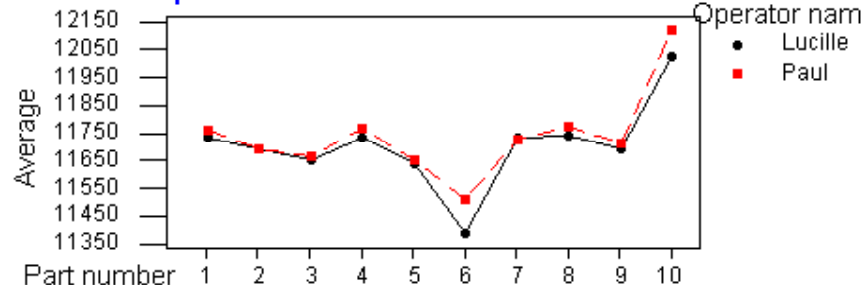
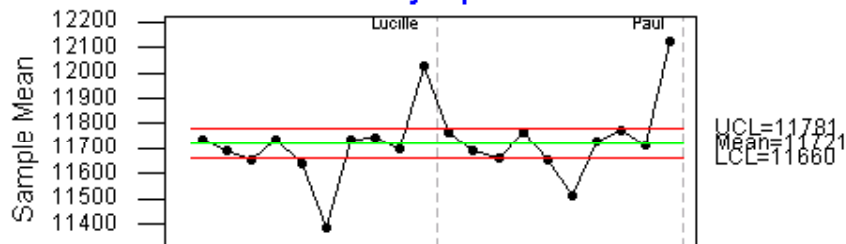
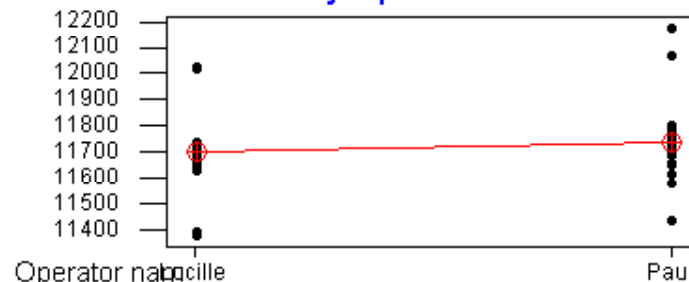
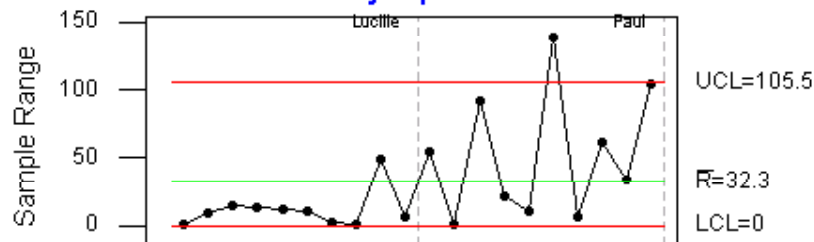
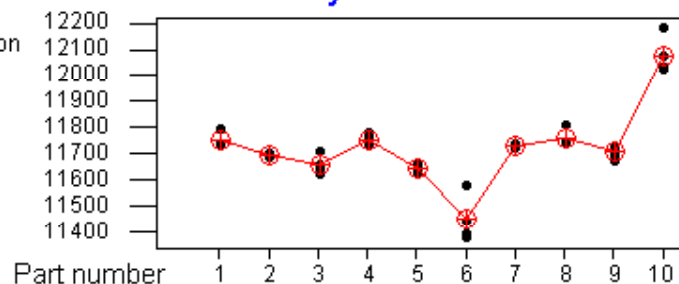
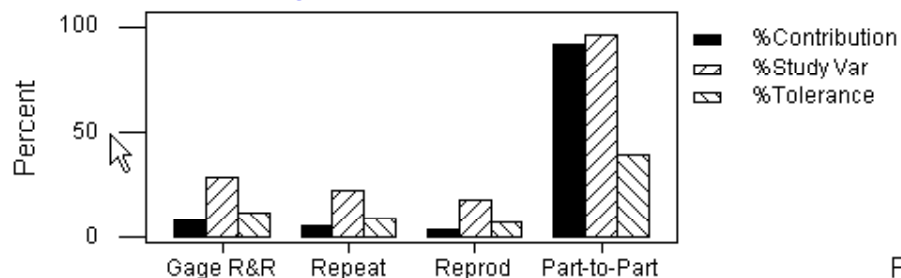
Control chart with measurement error.



Position of parts distribution where
60 parts = total tolerance
scale units = percentage from aim



Gage name: Nanometrics
Date of study: June 11, 1990
Reported by: Paul Yee
Tolerance: 2000
Misc: Resist Thickness



Gage R&R Study - ANOVA Method

Gage R&R for Measurement

Gage name: Nanometrics
Date of study: June 11, 1990
Reported by: Paul Yee
Tolerance: 2000
Misc: Resist Thickness

Two -Way ANOVA Table With Interaction

Source	DF	SS	MS	F	P
Part number	9	858523	95391.5	50.6934	0.00000
Operator nam	1	12461	12460.9	6.6220	0.03002
Operator nam*Part number	9	16936	1881.7	1.4865	0.21961
Repeatability	20	25318	1265.9		
Total	39	913238			

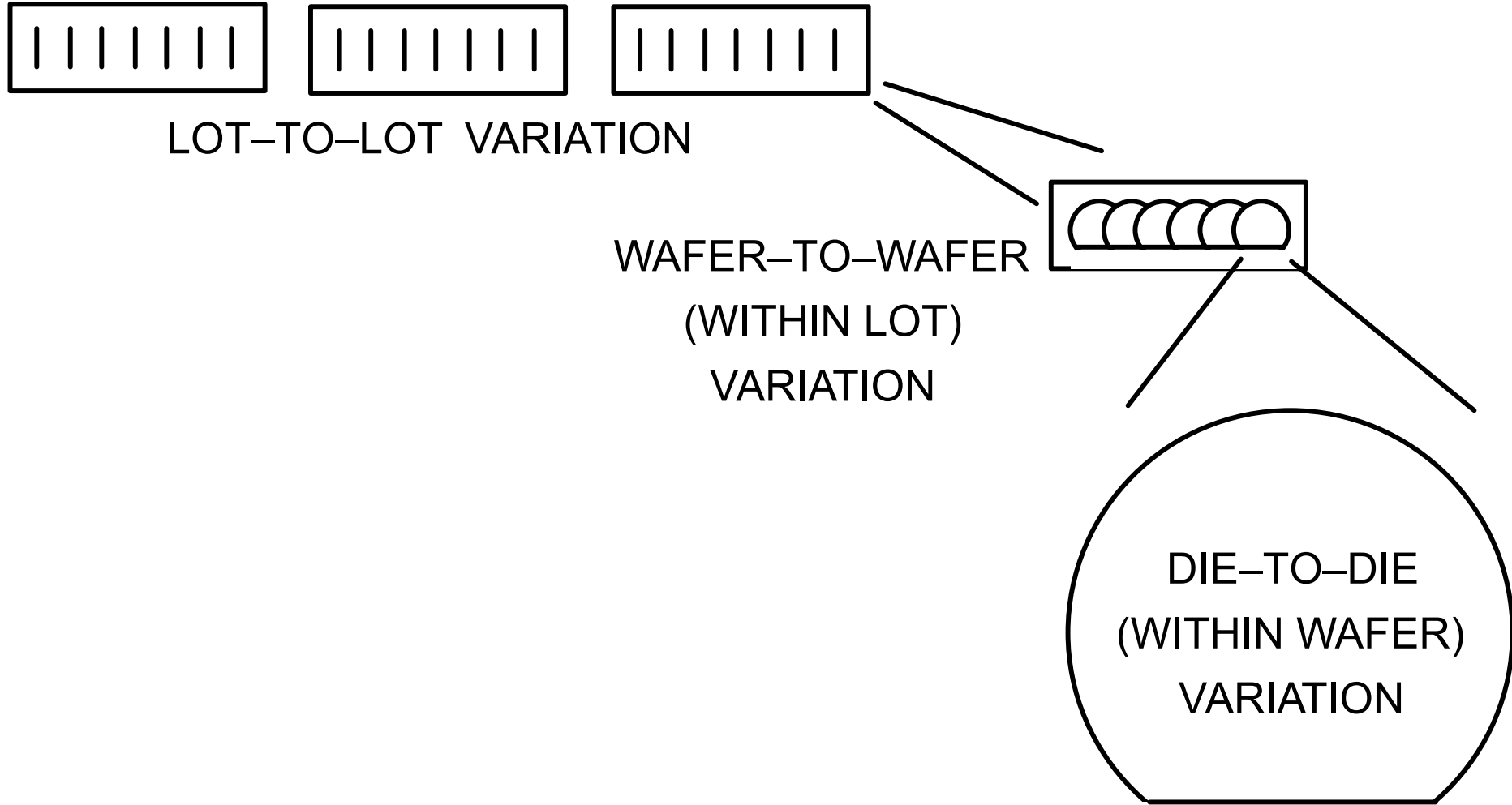
Gage R&R

Source	VarComp	%Contribution (of VarComp)
Total Gage R&R	2103	8.25
Repeatability	1266	4.97
Reproducibility	837	3.28
Operator nam	529	2.08
Operator nam*Part number	308	1.21
Part - To - Part	23377	91.75
Total Variation	25480	100.00

Source	StdDev (SD)	Study Var (5.15*SD)	%Study Var (%SV)	%Tolerance (SV/Toler)
Total Gage R&R	45.856	236.159	28.73	11.81
Repeatability	35.579	183.234	22.29	9.16
Reproducibility	28.929	148.983	18.12	7.45
Operator nam	22.999	118.445	14.41	5.92
Operator nam*Part number	17.548	90.370	10.99	4.52
Part - To - Part	152.897	787.419	95.78	39.37
Total Variation	159.625	822.070	100.00	41.10

Number of Distinct Categories = 5

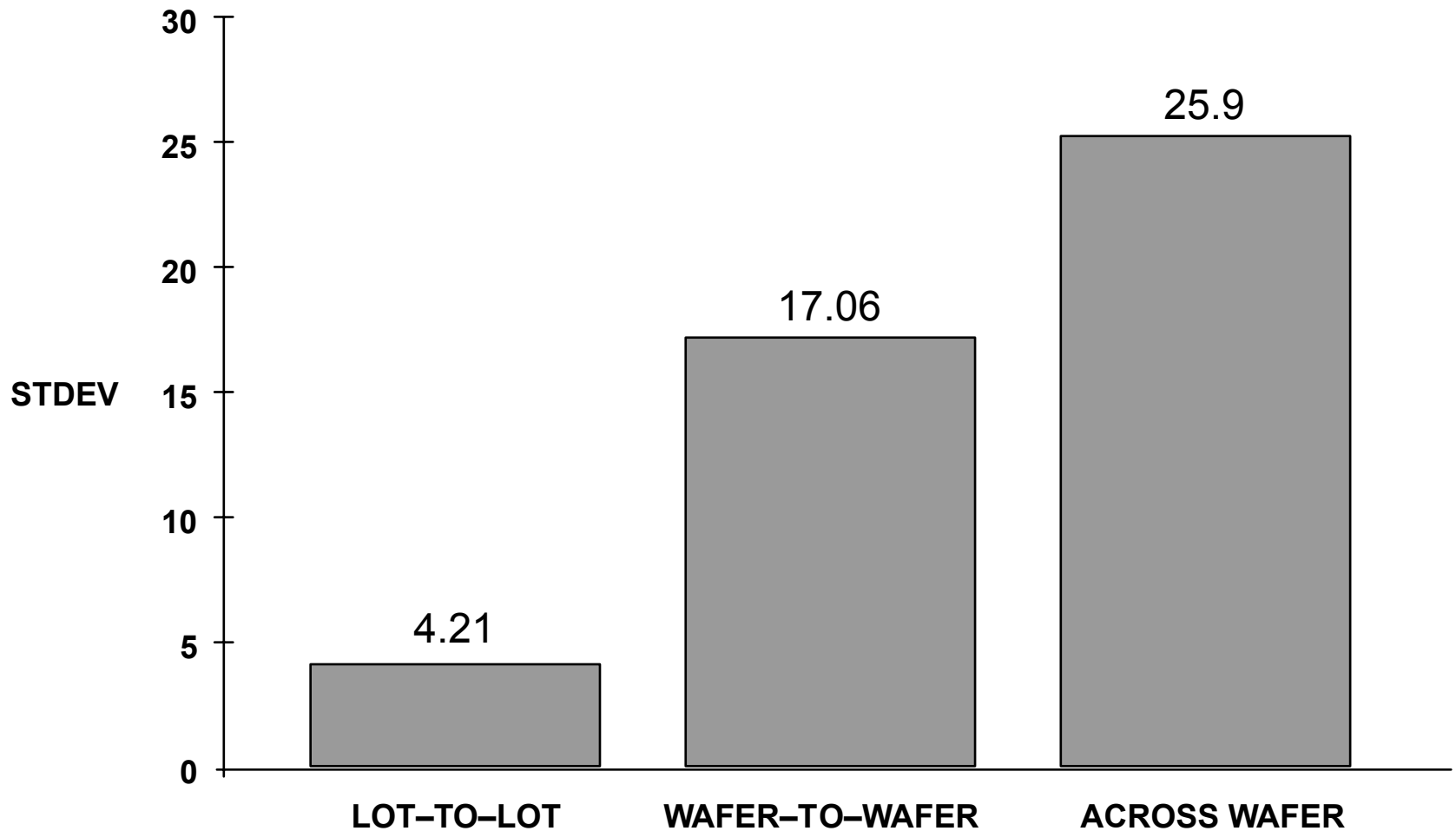
NESTED VARIANCE IN I.C. MANUFACTURING:



Symmetry Plot...

View 10:31 PM

63W H_{FE} VARIANCE COMPONENTS ANALYSIS



VARIANCE COMPONENTS ANALYSIS

DIE-TO-DIE VARIANCE:

DIE-TO-DIE VARIANCE = AVERAGE (VARIANCE ACROSS EACH WAFER)

WAFER-TO-WAFER VARIANCE:

If measurements on the same wafer are averaged repeatedly,
Variance of means = (Die-to-die variance) / N_d (Center Limit Theorem)

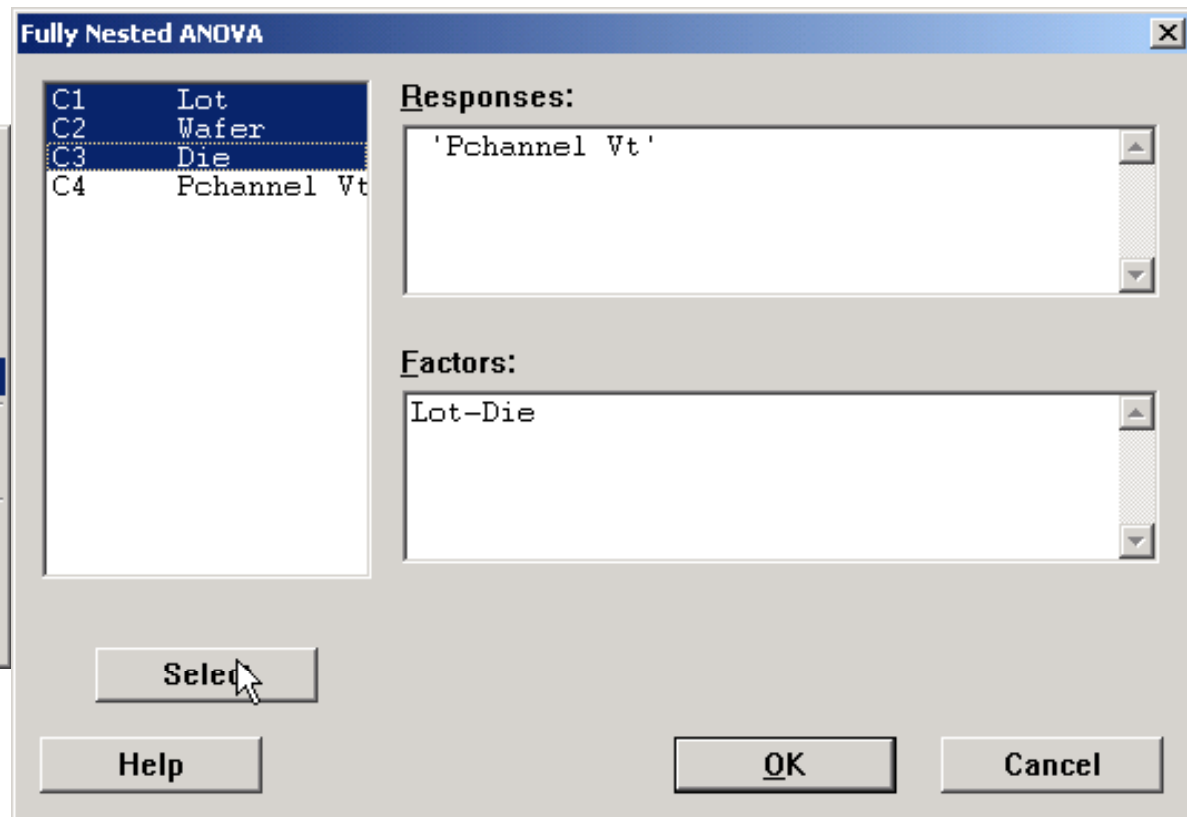
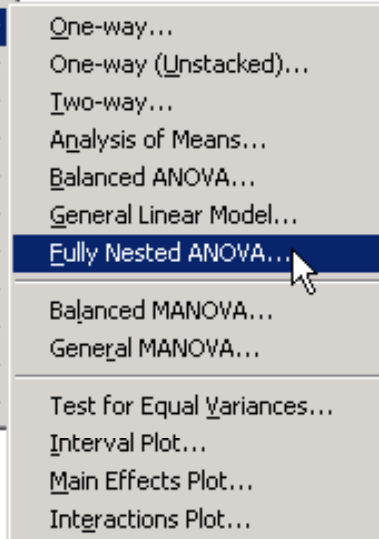
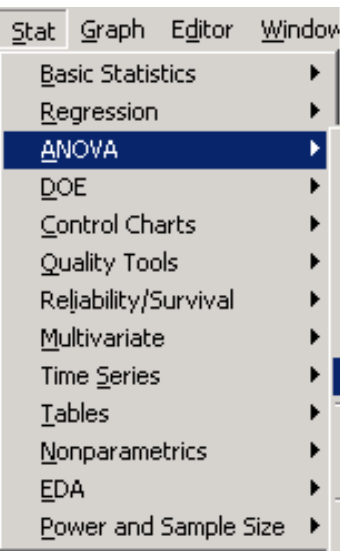
**Wafer-To-Wafer Variance = (Average of the variances of wafer means)
– (Die-to-die variance) / N_d**

LOT-TO-LOT VARIANCE:

**Lot-to-lot Variance = (Variance of lot means)
– (Average of the variances of wafer means) / N_w**

**TOTAL VARIANCE = DIE-TO-DIE VARIANCE
+ WAFER-TO-WAFER VARIANCE
+ LOT-TO-LOT VARIANCE**

NESTED ANALYSIS OF VARIANCE— MINITAB EXAMPLE



Nested ANOVA: Pchannel Vt versus Lot, Wafer, Die

Analysis of Variance for Pchannel

Source	DF	SS	MS	F	P
Lot	4	1568342.4642	392085.6160	25.071	0.000
Wafer	20	312782.2958	15639.1148	5.407	0.000
Die	100	289251.9864	2892.5199		
Total	124	2170376.7464			

Variance Components

Source	Var Comp.	% of Total	StDev
Lot	15057.860	73.45	122.710
Wafer	2549.319	12.44	50.491
Die	2892.520	14.11	53.782
Total	20499.699		143.177